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3-V To 5.5-V MULTICHANNEL RS-232 LINE DRIVER/RECEIVER WITH ±15-kV ESD PROTECTION

FEATURES

- Qualified for Automotive Applications
- RS-232 Bus-Pin ESD Protection Exceeds ±15 kV Using Human-Body Model (HBM)
- Meets or Exceeds the Requirements of TIA/EIA-232-F and ITU v.28 Standards
- Operates With 3-V to 5.5-V V_{CC} Supply
- · Operates up to 250 kbit/s
- Two Drivers and Two Receivers
- Low Standby Current . . . 1 μA Typical
- External Capacitors . . . 4 × 0.1 μF
- Accepts 5-V Logic Input With 3.3-V Supply

PW PACKAGE (TOP VIEW) 20 TORCEOFF 19 V_{CC} C1+||2 V+**∏**3 18 ∏ GND C1- ∏4 17 DOUT1 16 RIN1 C2+ ¶ 5 C2- [6 15 ROUT1 V- **∏** 7 14 ∏ FORCEON 13 DIN1 DOUT2 ¶8 12 DIN2 RIN2 ¶ 9 11 NVALID ROUT2 10

DESCRIPTION/ORDERING INFORMATION

The TRS3223 consists of two line drivers, two line receivers, and a dual charge-pump circuit with ± 15 -kV ESD protection pin to pin (serial-port connection pins, including GND). The device meets the requirements of TIA/EIA-232-F and provides the electrical interface between an asynchronous communication controller and the serial-port connector. The charge pump and four small external capacitors allow operation from a single 3-V to 5.5-V supply. The device operates at data signaling rates up to 250 kbit/s and a maximum of 30-V/ μ s driver output slew rate.

Flexible control options for power management are available when the serial port is inactive. The auto-powerdown feature functions when FORCEON is low and FORCEOFF is high. During this mode of operation, if the device does not sense a valid RS-232 signal, the driver outputs are disabled. If FORCEOFF is set low and \overline{EN} is high, both drivers and receivers are shut off, and the supply current is reduced to 1 μ A. Disconnecting the serial port or turning off the peripheral drivers causes auto-powerdown to occur. Auto-powerdown can be disabled when FORCEON and FORCEOFF are high. With auto-powerdown enabled, the device is activated automatically when a valid signal is applied to any receiver input. The INVALID output is used to notify the user if an RS-232 signal is present at any receiver input. INVALID is high (valid data) if any receiver input voltage is greater than 2.7 V or less than –2.7 V, or has been between –0.3 V and 0.3 V for less than 30 μ s. INVALID is low (invalid data) if the receiver input voltage is between –0.3 V and 0.3 V for more than 30 μ s. See Figure 4 for receiver input levels.

ORDERING INFORMATION(1)

T _A	PACK	AGE ⁽²⁾	ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 125°C	TSSOP – PW	Reel of 2000	TRS3223QPWRQ1	T3223

⁽¹⁾ For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.

(2) Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



DRIVER FUNCTION TABLE (EACH DRIVER)(1)

	II	NPUTS		OUTPUT			
DIN	FORCEON	FORCEOFF	VALID RIN RS-232 LEVEL	DOUT	DRIVER STATUS		
Х	X	L	X	Z	Powered off		
L	Н	Н	X	Н	Normal appration with outs powerdown dischlad		
Н	Н	Н	Х	L	Normal operation with auto-powerdown disabled		
L	L	Н	Yes	Н	Normal aparation with auto powardown applied		
Н	L	Н	Yes	L	Normal operation with auto-powerdown enabled		
L	L	Н	No	Z	Dowered off by outo newordown feature		
Н	L	Н	No	Z	Powered off by auto-powerdown feature		

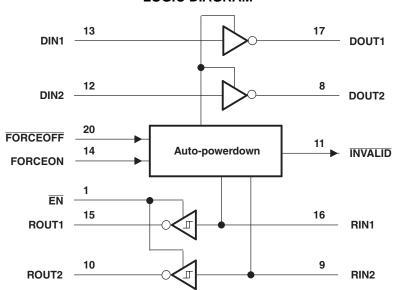
(1) H = high level, L = low level, X = irrelevant, Z = high impedance

RECEIVER FUNCTION TABLE (EACH RECEIVER)(1)

	INPUTS					
RIN	EN	VALID RIN RS-232 LEVEL	OUTPUT ROUT			
L	L	X	Н			
Н	L	X	L			
Х	Н	X	Z			
Open	L	No	Н			

(1) H = high level, L = low level, X = irrelevant, Z = high impedance (off), Open = input disconnected or connected driver off

LOGIC DIAGRAM



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ABSOLUTE MAXIMUM RATINGS(1)(2)

over operating free-air temperature range (unless otherwise noted)

V _{CC}	Supply voltage range		-0.3 V to 6 V
V+	Positive output supply voltage range		-0.3 V to 7 V
V-	Negative output supply voltage range	Negative output supply voltage range	
V+ - V-	Supply voltage difference	Supply voltage difference	
V	Innuit voltage range	Driver, FORCEOFF, FORCEON, EN	-0.3 V to 6 V
V _I	Input voltage range	Receiver	–25 V to 25 V
V	Output valtage range	Driver	–13.2 V to 13.2 V
Vo	Output voltage range	Receiver, INVALID	-0.3 V to V _{CC} + 0.3 V
θ_{JA}	Package thermal impedance (3)		83°C/W
TJ	Operating virtual-junction temperature		150°C
T _{stg}	Storage temperature range		−65°C to 150°C

Stresses beyond those listed under absolute maximum ratings may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under recommended operating conditions is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

RECOMMENDED OPERATING CONDITIONS(1)

see Figure 6

				MIN	NOM	MAX	UNIT
\/	Complement		$V_{CC} = 3.3 \text{ V}$	3	3.3	3.6	\/
V _{CC}	Supply voltage		$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$				
\/	/ High level innert values	Driver and control,	V _{CC} = 3.3 V	2			\/
V_{IH}	High-level input voltage	DIN, $\overline{\text{EN}}$, $\overline{\text{FORCEOFF}}$, FORCEON	V _{CC} = 5 V	2.4			V
V_{IL}	Low-level input voltage	Driver and control, DIN, EN, FORCEOFF	F, FORCEON			8.0	V
.,	lancit calta na	Driver and control, DIN, EN, FORCEOFF	F, FORCEON	0		5.5	
VI	Input voltage Receiver			-25		25	V
T_A	Operating free-air temperature			-40		125	°C

⁽¹⁾ Test conditions are C1–C4 = 0.1 μ F at V_{CC} = 3.3 V ± 0.3 V; C1 = 0.047 μ F, C2–C4 = 0.33 μ F at V_{CC} = 5 V ± 0.5 V.

ELECTRICAL CHARACTERISTICS(1)

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 6)

	PARAM	ETER	TES	ST CONDITIONS	MIN TYP(2)	MAX	UNIT
I _I	I _I Input leakage current		EN, FORCEOFF, FO	EN, FORCEOFF, FORCEON		±1	μΑ
		Auto-powerdown disabled		No load, FORCEOFF and FORCEON at V _{CC}	0.3	2	mA
Icc	Supply current	Powered off		No load, FORCEOFF at GND	1	20	
100	cupply current	Auto-powerdown enabled	T _A = 25°C	No load, FORCEOFF at V _{CC} , FORCEON at GND, All RIN are open or grounded	1	20	μΑ

Test conditions are C1–C4 = 0.1 μ F at V_{CC} = 3.3 V ± 0.3 V; C1 = 0.047 μ F, C2–C4 = 0.33 μ F at V_{CC} = 5 V ± 0.5 V. All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V, and T_A = 25°C.

All voltages are with respect to network GND.

The package thermal impedance is calculated in accordance with JESD 51-7.

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DRIVER SECTION ELECTRICAL CHARACTERISTICS(1)

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 6)

	PARAMETER	TE	ST CONDITIONS	MIN	TYP ⁽²⁾	MAX	UNIT
V_{OH}	High-level output voltage	DOUT at $R_L = 3 \text{ k}\Omega$ to GN	ND	5	5.4		V
V _{OL}	Low-level output voltage	DOUT at $R_L = 3 \text{ k}\Omega$ to GND		-5	-5.4		V
I _{IH}	High-level input current	$V_I = V_{CC}$			±0.01	±1	μΑ
I _{IL}	Low-level input current	V _I = GND			±0.01	±1	μΑ
	Short-circuit output current ⁽³⁾	$V_{CC} = 3.6 \text{ V}, V_{O} = 0 \text{ V}$			±35	±60	π Λ
los	Short-circuit output current	V _{CC} = 5.5 V, V _O = 0 V			±35	±60	mA
r _o	Output resistance	V_{CC} , V+, and V- = 0 V, V	O = ±2 V	300	10M		Ω
	Output lookage gurrent	FORCEOFF = GND	$V_{O} = \pm 12 \text{ V}, V_{CC} = 3 \text{ V to } 3.6 \text{ V}$			±25	
I _{off}	Output leakage current	age current $V_O = \pm 10 \text{ V}, V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$				±25	μΑ

⁽¹⁾ Test conditions are C1–C4 = 0.1 μ F at V_{CC} = 3.3 V \pm 0.3 V; C1 = 0.047 μ F, C2–C4 = 0.33 μ F at V_{CC} = 5 V \pm 0.5 V.

DRIVER SECTION SWITCHING CHARACTERISTICS(1)

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 6)

	PARAMETER	TEST CONDI	TIONS	MIN	TYP ⁽²⁾	MAX	UNIT
	Maximum data rate	$C_L = 1000 \text{ pF}$, One DOUT switching, $R_L = 3 \text{ k}\Omega$ (see Figure 1)		250			kbit/s
t _{sk(p)}	Pulse skew ⁽³⁾	C_L = 150 pF to 2500 pF, R_L = 3 k Ω to 7 k Ω (see Figure 2)			100		ns
CD/tr\	Slew rate, transition region	$V_{CC} = 3.3 \text{ V}, R_L = 3 \text{ k}\Omega \text{ to } 7 \text{ k}\Omega$	C _L = 150 pF to 1000 pF	6		30	V/us
SR(tr)	(see Figure 1)	$V_{CC} = 5.5 \text{ V}, R_L = 5 \text{ K} 10 \text{ / K} 12$	C _L = 150 pF to 2500 pF	4		30	V/μS

Test conditions are C1–C4 = 0.1 μ F at V_{CC} = 3.3 V \pm 0.3 V; C1 = 0.047 μ F, C2–C4 = 0.33 μ F at V_{CC} = 5 V \pm 0.5 V. All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V, and T_A = 25°C.

All typical values are at $V_{CC} = 3.3 \text{ V}$ or $V_{CC} = 5 \text{ V}$, and $T_A = 25 ^{\circ}\text{C}$.

Short-circuit durations should be controlled to prevent exceeding the device absolute power-dissipation ratings, and not more than one output should be shorted at a time.

Pulse skew is defined as |t_{PLH} - t_{PHL}| of each channel of the same device.

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RECEIVER SECTION ELECTRICAL CHARACTERISTICS(1)

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 6)

	PARAMETER	TEST CONDITIONS	MIN	TYP ⁽²⁾	MAX	UNIT
V_{OH}	High-level output voltage	$I_{OH} = -1 \text{ mA}$	V _{CC} - 0.6	$V_{CC} - 0.1$		V
V _{OL}	Low-level output voltage	I _{OL} = 1.6 mA			0.4	V
V	Desitive gains input threshold valtage	V _{CC} = 3.3 V		1.6	2.4	V
V _{IT+}	Positive-going input threshold voltage	V _{CC} = 5 V		1.9	2.4	V
V	Negative going input threshold voltage	V _{CC} = 3.3 V	0.6	1.1		V
V _{IT}	Negative-going input threshold voltage	V _{CC} = 5 V	0.8	1.4		V
V _{hys}	Input hysteresis (V _{IT+} – V _{IT} –)			0.5		V
I _{off}	Output leakage current	EN = V _{CC}		±0.05	±10	μΑ
ri	Input resistance	$V_I = \pm 3 \text{ V to } \pm 25 \text{ V}$	3	5	8.3	kΩ

⁽¹⁾ Test conditions are C1–C4 = 0.1 μ F at V_{CC} = 3.3 V \pm 0.3 V; C1 = 0.047 μ F, C2–C4 = 0.33 μ F at V_{CC} = 5 V \pm 0.5 V. (2) All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V, and T_A = 25°C.

RECEIVER SECTION SWITCHING CHARACTERISTICS(1)

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 6)

	PARAMETER	TEST CONDITIONS	TYP ⁽²⁾	UNIT
t _{PLH}	Propagation delay time, low-level to high-level output	C _L = 150 pF, See Figure 3	150	ns
t _{PHL}	Propagation delay time, high-level to low-level output	C _L = 150 pF, See Figure 3	150	ns
t _{en}	Output enable time	$C_L = 150 \text{ pF}, R_L = 3 \text{ k}\Omega, \text{ See Figure 4}$	200	ns
t _{dis}	Output disable time	$C_L = 150 \text{ pF}, R_L = 3 \text{ k}\Omega, \text{ See Figure 4}$	200	ns
t _{sk(p)}	Pulse skew ⁽³⁾	See Figure 3	50	ns

Test conditions are C1–C4 = 0.1 μ F at V_{CC} = 3.3 V ± 0.3 V; C1 = 0.047 μ F, C2–C4 = 0.33 μ F at V_{CC} = 5 V ± 0.5 V. All typical values are at V_{CC} = 3.3 V or V_{CC} = 5 V, and T_A = 25°C. Pulse skew is defined as $|t_{PLH} - t_{PHL}|$ of each channel of the same device.

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AUTO-POWERDOWN SECTION ELECTRICAL CHARACTERISTICS

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 5)

	PARAMETER	TEST CONDITIONS	MIN	MAX	UNIT
V _{T+(valid)}	Receiver input threshold for INVALID high-level output voltage	FORCEON = GND, FORCEOFF = V _{CC}		2.7	V
V _{T-(valid)}	Receiver input threshold for INVALID high-level output voltage	FORCEON = GND, FORCEOFF = V _{CC}	-2.7		V
V _{T(invalid)}	Receiver input threshold for INVALID low-level output voltage	FORCEON = GND, FORCEOFF = V _{CC}	-0.3	0.3	V
V _{OH}	INVALID high-level output voltage	$I_{OH} = -1$ mA, FORCEON = GND, FORCEOFF = V_{CC}	V _{CC} - 0.6		V
V_{OL}	INVALID low-level output voltage	$I_{OL} = 1.6 \text{ mA}, FORCEON = GND}, \overline{FORCEOFF} = V_{CC}$		0.4	V

AUTO-POWERDOWN SECTION SWITCHING CHARACTERISTICS

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 5)

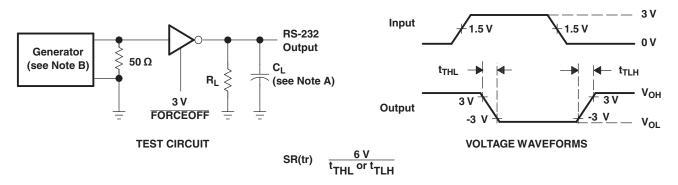
	PARAMETER	TYP ⁽¹⁾	UNIT
t _{valid}	Propagation delay time, low- to high-level output	1	μs
t _{invalid}	Propagation delay time, high- to low-level output	30	μs
t _{en}	Supply enable time	100	μs

⁽¹⁾ All typical values are at $V_{CC} = 3.3 \text{ V}$ or $V_{CC} = 5 \text{ V}$, and $T_A = 25 ^{\circ}\text{C}$.



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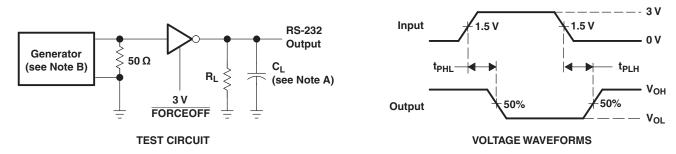
PARAMETER MEASUREMENT INFORMATION



A.C_L includes probe and jig capacitance.

B.The pulse generator has the following characteristics: PRR = 250 kbit/s, $Z_0 = 50 \Omega$, 50% duty cycle, $t_i \le 10$ ns. $t_i \le 10$ ns.

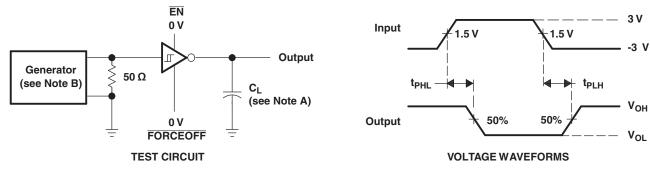
Figure 1. Driver Slew Rate



A.C_L includes probe and jig capacitance.

B.The pulse generator has the following characteristics: PRR = 250 kbit/s, $Z_O = 50 \Omega$, 50% duty cycle, $t_i \le 10$ ns.

Figure 2. Driver Pulse Skew



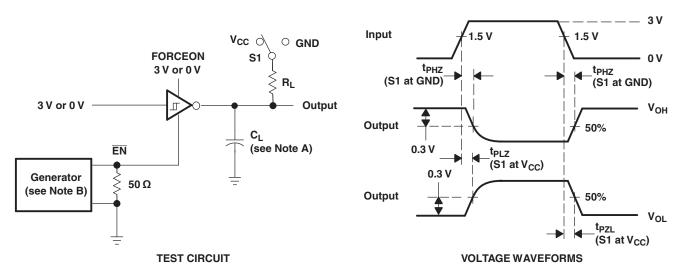
A.C_L includes probe and jig capacitance.

B.The pulse generator has the following characteristics: $Z_0 = 50 \Omega$, 50% duty cycle, $t_r \le 10$ ns. $t_f \le 10$ ns.

Figure 3. Receiver Propagation Delay Times



PARAMETER MEASUREMENT INFORMATION (continued)



A.C_L includes probe and jig capacitance.

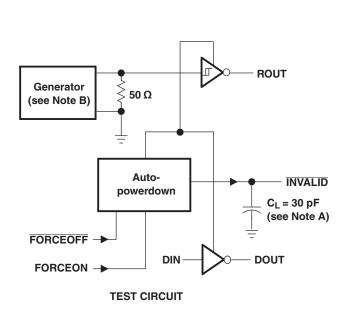
B.The pulse generator has the following characteristics: $Z_O = 50 \Omega$, 50% duty cycle, $t_f \le 10$ ns. $t_f \le 10$ ns.

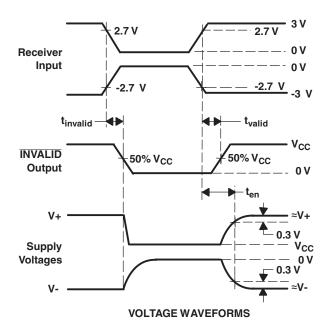
Figure 4. Receiver Enable and Disable Times

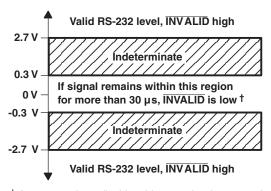


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PARAMETER MEASUREMENT INFORMATION (continued)







 $^{^\}dagger$ Auto-powerdown disables drivers and reduces supply current to 1 $\mu A.$

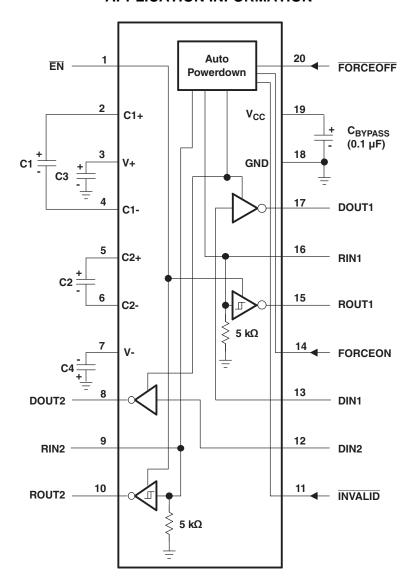
B.The pulse generator has the following characteristics: PRR = 5 kbit/s, $Z_O = 50 \Omega$, 50% duty cycle, $t_f \le 10$ ns. $t_f \le 10$ ns.

Figure 5. INVALID Propagation Delay Times and Supply Enabling Time

A.C_L includes probe and jig capacitance.



APPLICATION INFORMATION



- A.C3 can be connected to $V_{\mbox{\footnotesize CC}}$ or GND.
- B.Resistor values shown are nominal.
- C.Nonpolarized ceramic capacitors are acceptable. If polarized tantalum or electrolytic capacitors are used, they should be connected as shown.

V_{CC} vs CAPACITOR VALUES

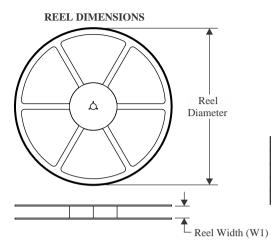
V _C	С	C1	C2, C3, C4		
3.3 V ±	0.5 V	0.1 μF	0.1 μF		
5 V ± 0		0.047 μF	0.33 μF		
3 V to		0.1 μF	0.47 μF		

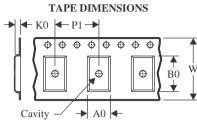
Figure 6. Typical Operating Circuit and Capacitor Values

PACKAGE MATERIALS INFORMATION

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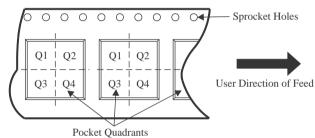
TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

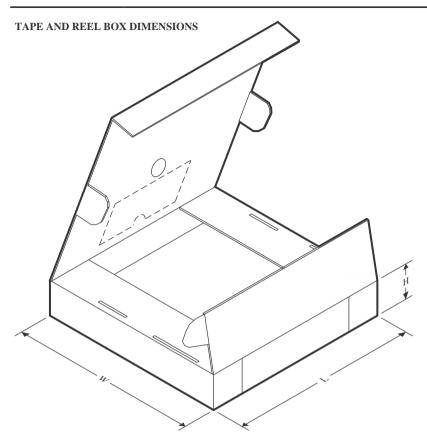


*All dimensions are nominal

Device	U	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TRS3223QPWRQ1	TSSOP	PW	20	2000	330.0	16.4	6.95	7.0	1.4	8.0	16.0	Q1

PACKAGE MATERIALS INFORMATION

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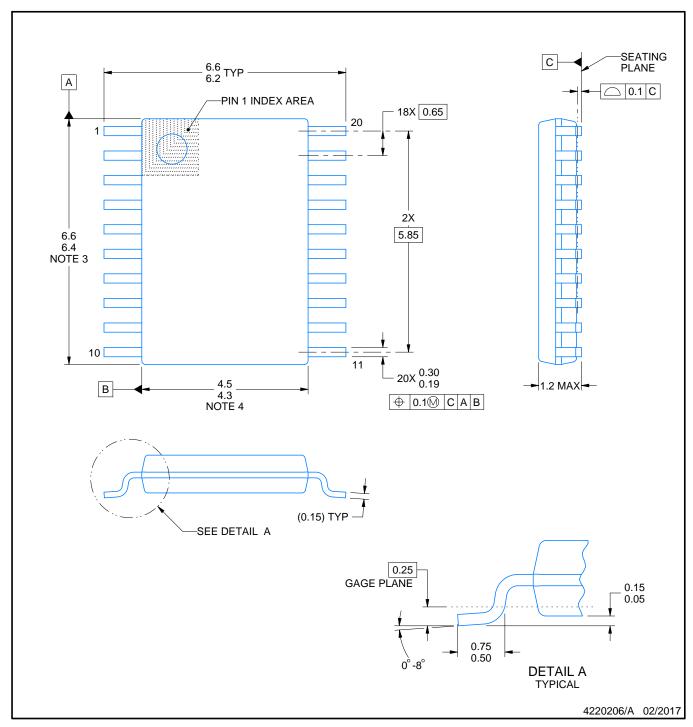


*All dimensions are nominal

Ì	Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)	
ı	TRS3223QPWRQ1	TSSOP	PW	20	2000	356.0	356.0	35.0	



SMALL OUTLINE PACKAGE



NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
- 5. Reference JEDEC registration MO-153.



SMALL OUTLINE PACKAGE



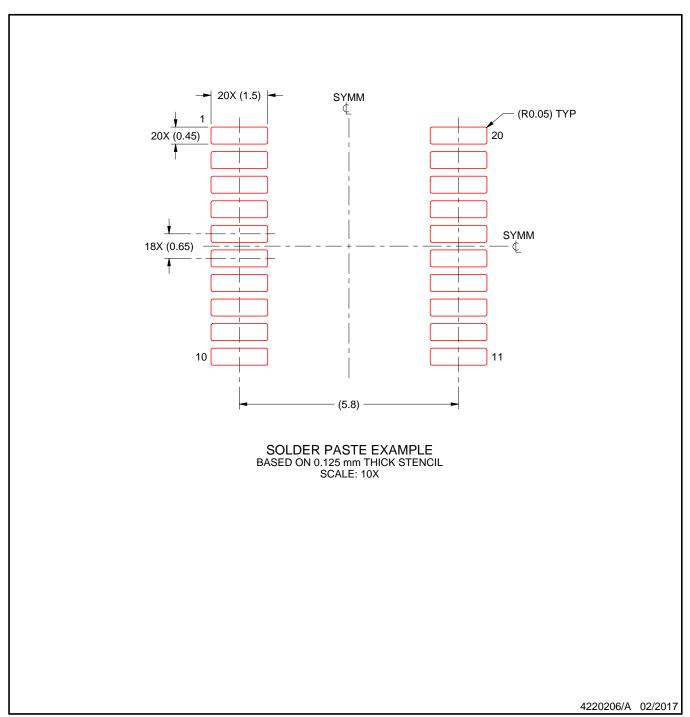
NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE PACKAGE



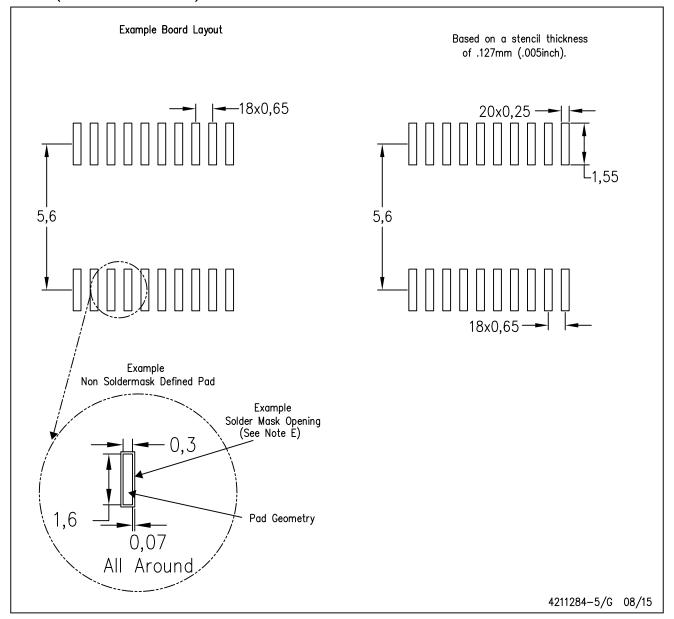
NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



PW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



NOTES:

- All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.C. Publication IPC-7351 is recommended for alternate design.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



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